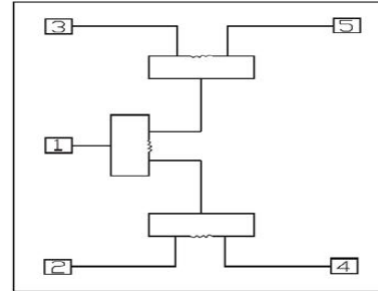


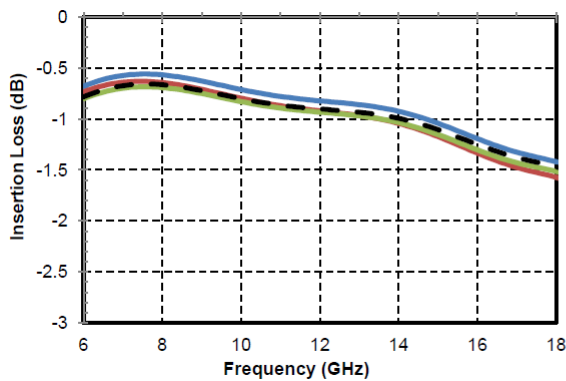
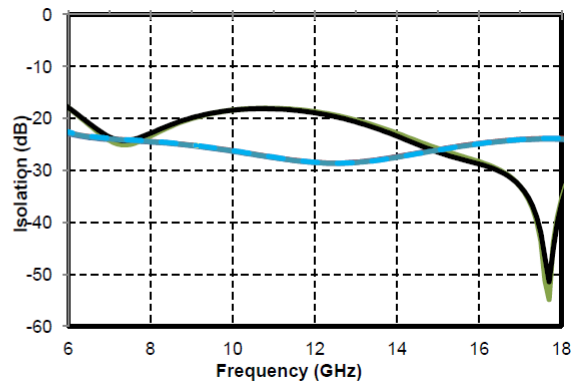
Features

- Frequency: 6-18GHz
- Insertion Loss: 1.0dB
- Input/Output: 50Ω matched
- Die Size: 1.8 x 1.1 x 0.1 mm

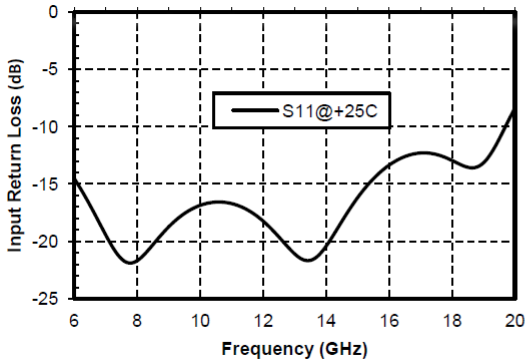
Functional Block Diagram

Electrical Specifications

TA = +25°C

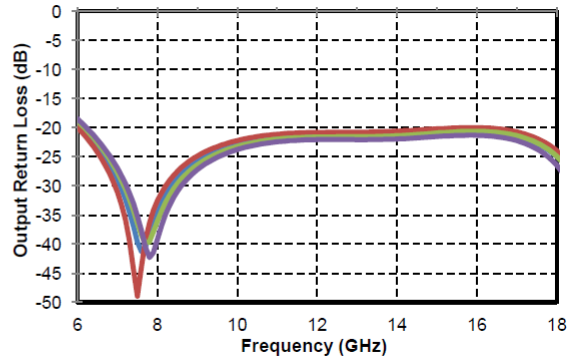
Parameters	Min.	Typ.	Max.	Units
Frequency	6-18			GHz
Insertion Loss	0.7	1.0	1.5	dB
Flatness		±0.4		dB
Isolation	17	22		dB
Input Return Loss	12	15		dB
Output Return Loss	18	21		dB

Insertion Loss

Isolation


Input Return Loss

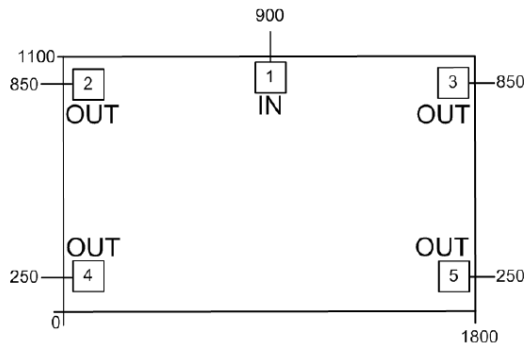


Output Return Loss

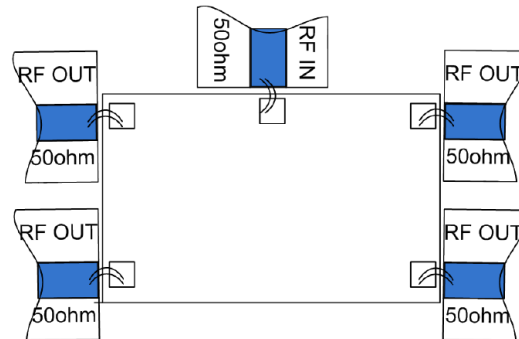


Outline Drawing

All Dimensions in um



Assembly Drawing



Pad Description

Pad	Function	Description
1	RF IN	RF Input Port
2,3,4,5	RF OUT	RF Output Port
Die bottom	GND	Die bottom must be connected to RF/DC ground.

Maximum Ratings:

1. Maximum input power: +40dBm
2. Operating temperature: -55°C to +85°C
3. Storage temperature: -65°C to +150°C